

**EAST Search History****EAST Search History (Prior Art)**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3	((printed with circuit with board) or (circuit with board or pcb) and (((trench or trace) with vias) and (dielectric or insulator\$3) and primer)	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2010/10/09 11:54
L2	1205	(426/596).COLS.	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/10/09 11:55
L8	561	(426/607).COLS.	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/10/09 12:01
L10	1271	(426/626).COLS.	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/10/09 12:02
S10	6	((HANNES) near2 (HORMANN)).INV.	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 19:07
S51	843	S50 and (horizontal with (technique or method))	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2009/05/13 11:30
S53	371	(205/80).COLS.	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 09:32
S54	0	(219/121.690).COLS.	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 09:33
S57	3654	(426/209).COLS.	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 09:35
S62	3705	(428/209).COLS.	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/11/02 09:44
S70	250429	*428*\$/cds.	US_PGPUB; USPAT; USOCR	ADJ	ON	2009/11/02 15:35
S73	252550	*428*\$/cds.	US_PGPUB; USPAT; USOCR	ADJ	ON	2010/01/11 18:25
S74	4673	S73 and (pcb or (print\$3 circuit board))	US_PGPUB; USPAT; USOCR	ADJ	ON	2010/01/11 18:27
S75	2638	S74 and @pdc="20040129"	US_PGPUB; USPAT; USOCR	ADJ	ON	2010/01/11 18:28
S76	7	S75 and (via or vias) and (trench or recess) and trace	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2010/01/11 18:29

S79	8352	(29/830,831,832,852).CCLS.	US_PGPUB; USPAT; USOCR; FFPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/01/21 16:52
S80	47	S79 and (PCB or (print\$3 circuit board)) and traces and dielectric and (laser ablation)	US_PGPUB; USPAT; USOCR; FFPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/01/21 16:53
S86	31	(high density interconnection) and (PCB or (print\$3 circuit board)) and ((copper or metal) adj layer) and dielectric and (laser ablation)	US_PGPUB; USPAT; USOCR; FFPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/01/21 18:29
S89	8586	(29/830,831,832,852).CCLS.	US_PGPUB; USPAT; USOCR; FFPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/06/18 18:53
S90	97	S89 and (PCB or (print\$3 circuit board)) and ((copper or metal) adj layer) and dielectric and (laser ablation)	US_PGPUB; USPAT; USOCR; FFPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/06/18 18:53
S98	3651	(29/846).CCLS.	US_PGPUB; USPAT; USOCR; FFPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/06/18 20:38
S103	4845	(257/40).CCLS.	US_PGPUB; USPAT; USOCR; FFPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/06/19 10:15
S105	3651	(29/846).CCLS.	US_PGPUB; USPAT; USOCR; FFPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/06/19 10:52
S106	1976	S105 and ((printed with circuit with board) or (circuit with board) or pcb)	US_PGPUB; USPAT; USOCR; FFPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2010/06/19 10:52
S107	323	S106 and (laser with (ablat\$3 or remov \$3))	US_PGPUB; USPAT; USOCR; FFPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/06/19 10:53
S108	208	S106 and (laser with (ablat\$3 or remov \$3)) and @ay<"2005"	US_PGPUB; USPAT; USOCR; FFPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/06/19 10:53
S111	14	"29".\$cls. and (vias with V-shape)	US_PGPUB; USPAT; USOCR; FFPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/06/19 14:34
S112	8586	(29/830,831,832,852).CCLS.	US_PGPUB; USPAT; USOCR; FFPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/06/19 14:35
S114	3	"428".\$cls. and (vias with V-shape)	US_PGPUB; USPAT; USOCR; FFPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/06/19 14:37
S115	3	"428".\$cls. and ((vias or trench or trace) with V-shape)	US_PGPUB; USPAT; USOCR; FFPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/06/19 14:37
S116	3651	(29/846).CCLS.	US_PGPUB; USPAT; USOCR; FFPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/06/19 14:38

S121	36	((REINHARD) near2 (SCHNEIDER)).INV.	US_PGPUB; USPAT; USOCR	ADJ	ON	2010/10/07 16:08
S122	30	((DAVID) near2 (BARON)).INV.	US_PGPUB; USPAT; USOCR	ADJ	ON	2010/10/07 16:10
S128	2173	((printed with circuit with board) or (circuit with board) or pcb) and (trend \$2) and vias	US_PGPUB; USPAT; USOCR; FPIRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2010/10/07 16:17
S129	1959	S128 and (dielectric or insulat\$3)	US_PGPUB; USPAT; USOCR; FPIRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2010/10/07 16:17
S130	83	S129 and (primer) and (metal near layer)	US_PGPUB; USPAT; USOCR; FPIRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2010/10/07 16:18
S131	230	S129 and (laser near ablat\$3)	US_PGPUB; USPAT; USOCR; FPIRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2010/10/07 16:48
S132	213	S131 not S130	US_PGPUB; USPAT; USOCR; FPIRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/07 16:58

**EAST Search History (Interference)**

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10/9/2010 12:35:30 PM

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